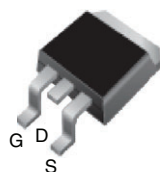


E Series Power MOSFET

D²PAK (TO-263)


N-Channel MOSFET

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low effective capacitance ($C_{o(er)}$)
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

PRODUCT SUMMARY

| | | |
|---|-----------------|-------|
| V_{DS} (V) at T_J max. | 700 | |
| $R_{DS(on)}$ typ. (Ω) at 25 °C | $V_{GS} = 10$ V | 0.056 |
| Q_g max. (nC) | 132 | |
| Q_{gs} (nC) | 24 | |
| Q_{gd} (nC) | 22 | |
| Configuration | Single | |

ORDERING INFORMATION

| | |
|---------------------------------|-----------------------------|
| Package | D ² PAK (TO-263) |
| Lead (Pb)-free and halogen-free | SiHB065N65E-GE3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|------------------|----------------|----------------|
| Drain-source voltage | V_{DS} | 650 | V |
| Gate-source voltage | V_{GS} | ± 30 | |
| Continuous drain current ($T_J = 150$ °C) | V_{GS} at 10 V | $T_C = 25$ °C | A |
| | | $T_C = 100$ °C | |
| Pulsed drain current ^a | I_{DM} | 124 | |
| Linear derating factor | | 2.0 | W/°C |
| Single pulse avalanche energy ^b | E_{AS} | 249 | mJ |
| Maximum power dissipation | P_D | 250 | W |
| Operating junction and storage temperature range | | T_J, T_{stg} | -55 to +150 °C |
| Drain-source voltage slope | dv/dt | $T_J = 125$ °C | V/ns |
| Reverse diode dv/dt ^d | | | |
| Soldering recommendations (peak temperature) ^c | For 10 s | 260 | °C |


Notes

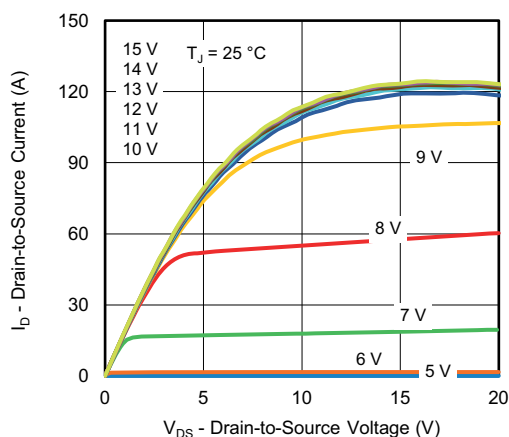
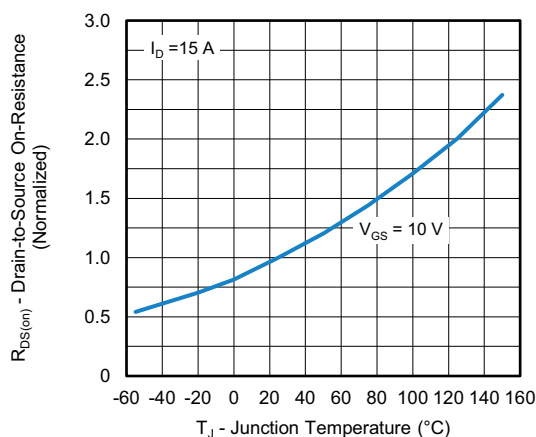
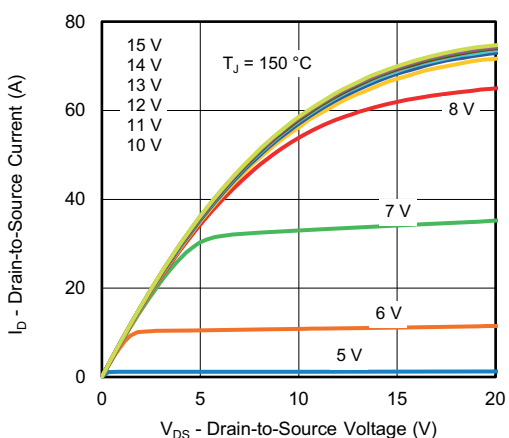
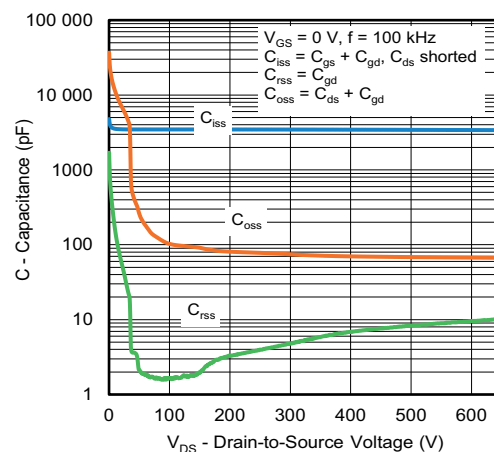
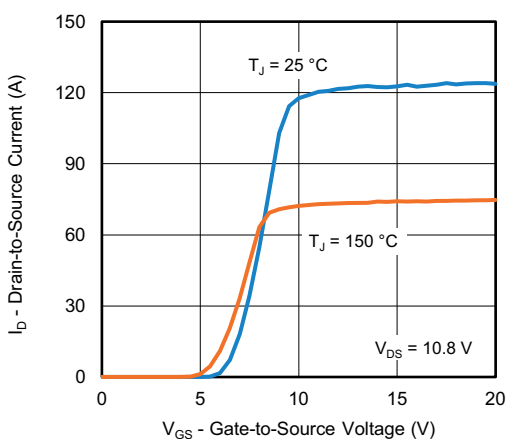
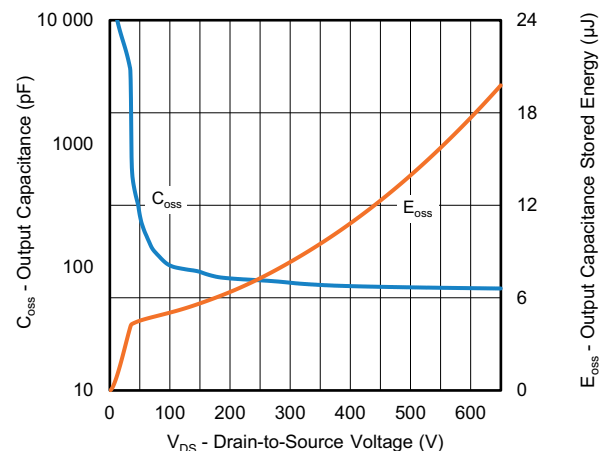
- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 120$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 4.2$ A
- 1.6 mm from case
- $I_{SD} \leq I_D$, $di/dt = 170$ A/ μ s, starting $T_J = 25$ °C

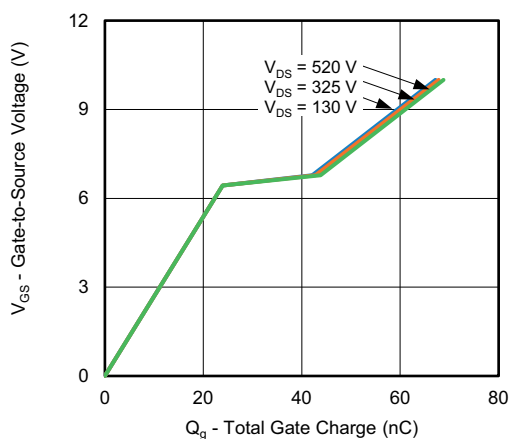
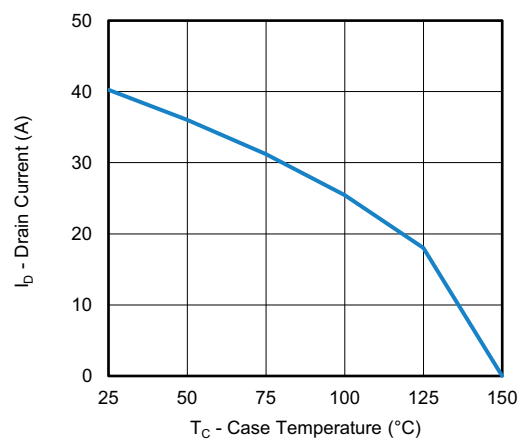
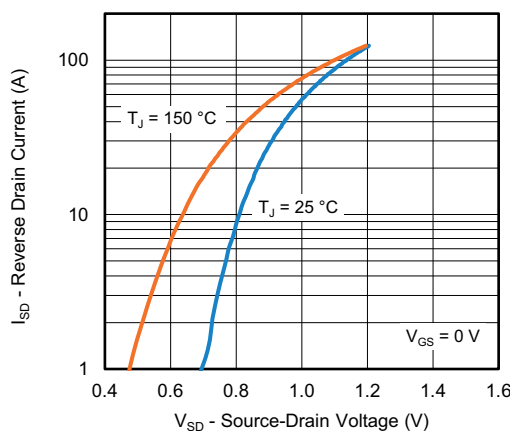
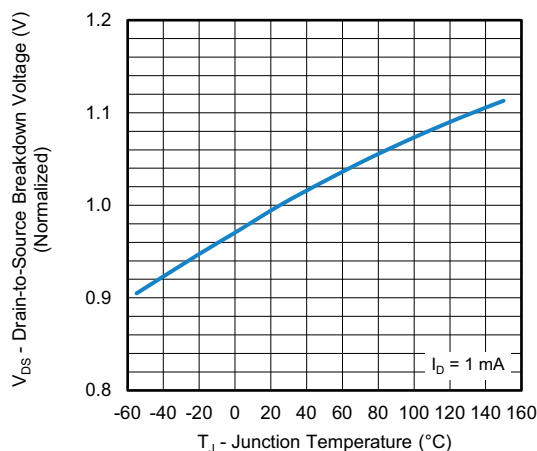
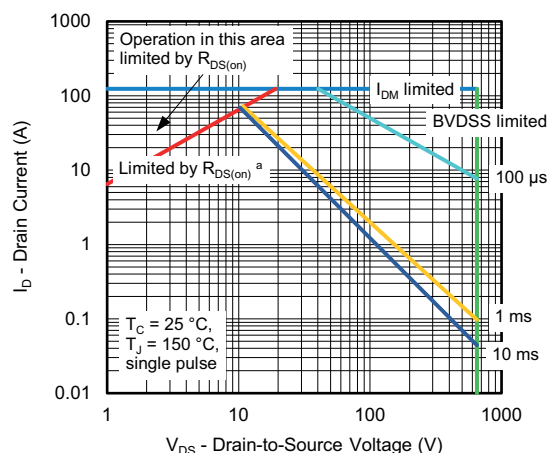
**THERMAL RESISTANCE RATINGS**

| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum junction-to-ambient | R_{thJA} | - | 62 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 0.5 | |

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|--|---------------------|--|---|------|-------|-----------|-----------------------|
| Static | | | | | | | |
| Drain-source breakdown voltage | V_{DS} | $V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$ | | 650 | - | - | V |
| V_{DS} temperature coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^{\circ}\text{C}$, $I_D = 1\text{ mA}$ | | - | 0.68 | - | V/ $^{\circ}\text{C}$ |
| Gate-source threshold voltage (N) | $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | | 3.0 | - | 5.0 | V |
| Gate-source leakage | I_{GSS} | $V_{GS} = \pm 20\text{ V}$ | | - | - | ± 100 | nA |
| | | $V_{GS} = \pm 30\text{ V}$ | | - | - | ± 1 | μA |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 650\text{ V}$, $V_{GS} = 0\text{ V}$ | | - | - | 1 | μA |
| | | $V_{DS} = 520\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$ | | - | - | 10 | |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 15\text{ A}$ | - | 0.056 | 0.065 | Ω |
| Forward transconductance | g_{fs} | $V_{DS} = 10\text{ V}$, $I_D = 15\text{ A}$ | | - | 16 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C_{iss} | $V_{GS} = 0\text{ V}$, $V_{DS} = 100\text{ V}$, $f = 100\text{ KHz}$ | | - | 3500 | - | pF |
| Output capacitance | C_{oss} | | | - | 124 | - | |
| Reverse transfer capacitance | C_{rss} | | | - | 2 | - | |
| Effective output capacitance, energy related | $C_{o(er)}$ | $V_{DS} = 0\text{ V to } 400\text{ V}$, $V_{GS} = 0\text{ V}$ | | - | 135 | - | pF |
| Effective output capacitance, time related | $C_{o(tr)}$ | | | - | 959 | - | |
| Total gate charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 15\text{ A}$, $V_{DS} = 520\text{ V}$ | - | 66 | 132 | nC |
| Gate-source charge | Q_{gs} | | | - | 24 | - | |
| Gate-drain charge | Q_{gd} | | | - | 22 | - | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 520\text{ V}$, $I_D = 17.3\text{ A}$, $V_{GS} = 10\text{ V}$, $R_g = 10.1\text{ }\Omega$ | | - | 35 | 70 | ns |
| Rise time | t_r | | | - | 40 | 80 | |
| Turn-off delay time | $t_{d(off)}$ | | | - | 74 | 148 | |
| Fall time | t_f | | | - | 13 | 26 | |
| Gate input resistance | R_g | $f = 1\text{ MHz}$, open drain | | 0.4 | 0.9 | 1.8 | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous source-drain diode current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 40 | A |
| Pulsed diode forward current | I_{SM} | | | - | - | 124 | |
| Diode forward voltage | V_{SD} | $T_J = 25\text{ }^{\circ}\text{C}$, $I_S = 15\text{ A}$, $V_{GS} = 0\text{ V}$ | | - | - | 1.2 | V |
| Reverse recovery time | t_{rr} | $T_J = 25\text{ }^{\circ}\text{C}$, $I_F = I_S = 15\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$ | | - | 317 | 634 | ns |
| Reverse recovery charge | Q_{rr} | | | - | 4.4 | 8.8 | μC |
| Reverse recovery current | I_{RRM} | | | - | 24 | - | A |

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 8 - Typical Source-Drain Diode Forward Voltage

Fig. 10 - Temperature vs. Drain-to-Source Voltage

Fig. 11 - Maximum Safe Operating Area
Note

a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

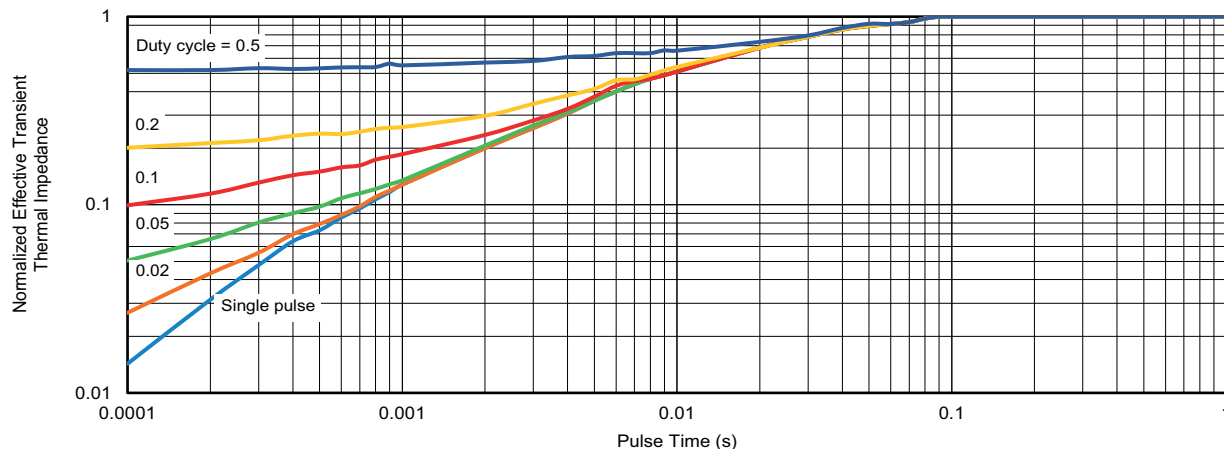
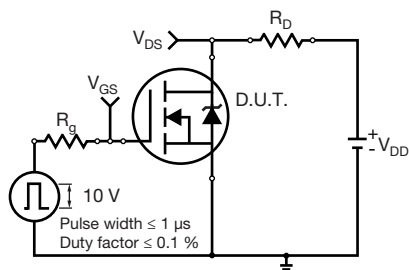
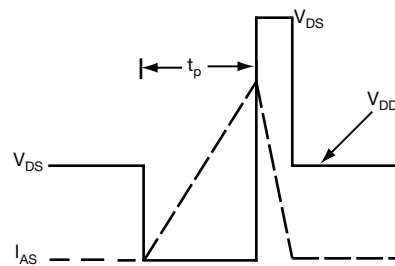
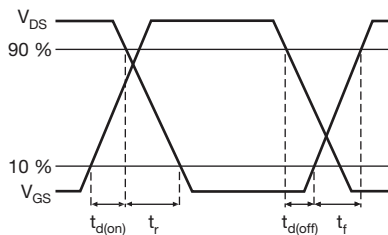
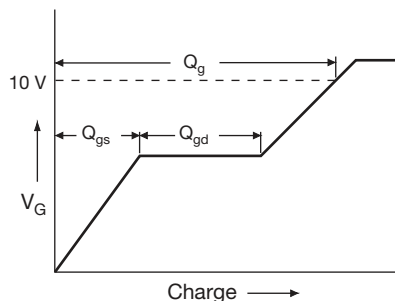
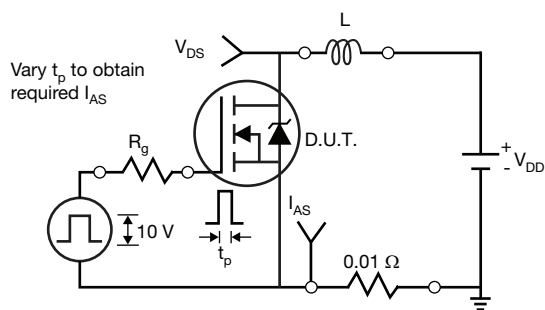
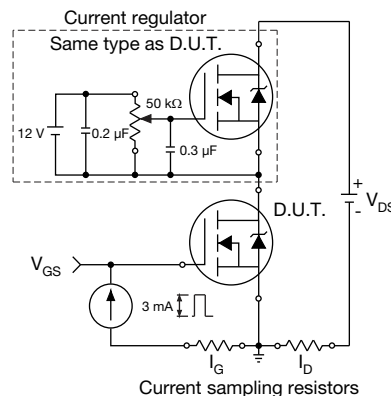

Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

Fig. 13 - Switching Time Test Circuit

Fig. 16 - Unclamped Inductive Waveforms

Fig. 14 - Switching Time Waveforms

Fig. 17 - Basic Gate Charge Waveform

Fig. 15 - Unclamped Inductive Test Circuit

Fig. 18 - Gate Charge Test Circuit



Fig. 19 - For N-Channel

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| | MILLIMETERS | | INCHES | |
|------|-------------|-------|-----------|-------|
| DIM. | MIN. | MAX. | MIN. | MAX. |
| D1 | 6.86 | - | 0.270 | - |
| E | 9.65 | 10.67 | 0.380 | 0.420 |
| E1 | 6.22 | - | 0.245 | - |
| e | 2.54 BSC | | 0.100 BSC | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | - | 1.65 | - | 0.066 |
| L2 | - | 1.78 | - | 0.070 |
| L3 | 0.25 BSC | | 0.010 BSC | |
| L4 | 4.78 | 5.28 | 0.188 | 0.208 |



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